MILESTONES

2011

- Tessera Creates New Invensas™ and DigitalOptics™ Groups
- Tessera Licenses OptiML™ Zoom Solution to Samsung
- SEMI Recognizes Developers of Tessera Chip-Scale Packaging Technology
- Tessera Licenses Patents to Olympus Imaging
- Tessera Licenses New Video Tools Solution to Fujitsu Semiconductor

2010

- Fujitsu renews technology licensing agreement with Tessera
- New Tessera technology brings video image stabilization to mobile market
- Tessera acquires Siimpel
- Tessera licenses Face Tracking technology to Samsung
- Tessera licenses OptiML Focus technology to AzureWave
- Tessera and UTAC sign updated technology licensing agreement
- Tessera and Nanium sign packaging technology agreement
- Tessera® OptiML image enhancement technologies in Samsung HD image sensors
- Tessera licenses Face Tracking technology to SK Telesys
- Tessera licenses OptiML Micro Via Pad technology to JCAP
- Tessera ships one millionth OptiML lens

2009

- New Tessera technology enables face recognition for mobile devices
- Tessera develops 3MP wafer-level optics technology with EDOF
- Tessera and Motorola enter into technology license agreement
- Tessera acquires certain assets from Dblur
- Tessera OptiML image enhancement solutions for up to 14MP
- Tessera offers OptiML lens array technology for parallel optics
- Tessera licenses wafer-level optics to Qtech
- Tessera licenses µPILR™ technology to Kinsus

2008

- Tessera's OptiML wafer-level camera technology recognized for photonics innovation
- Tessera’s wafer-level packaging technology shipped in one billion image sensors
- Tessera introduces new Face Beautification and Blink Detect technologies
- Tessera licenses OptiML Micro Via Pad technology to Qtech
- Tessrea licenses OptiML Micro Via Pad technology to AWLP and Qtech
- Tessera’s Face Tracking technology ships in Fujitsu chips
- Tessera introduces new Product Launch Services; offers OptiML single-element VGA lens
- Casio licenses Tessera’s Face Tracking technology
- R&D Magazine recognizes OptiML wafer-level camera technology in 2008 R&D 100 Awards
- Advanced Packaging Magazine honors Tessera’s wafer-level camera and wafer-level packaging technologies
- Samsung licenses OptiML Focus technology
- Tessera introduces OptiML Micro Via Pad wafer-level packaging technology for image sensors
- Tessera introduces OptiML Low Light, OptiML Zoom, OptiML Focus image enhancement solutions
- EDN Magazine honors OptiML wafer-level camera technology
- Tessera acquires FotoNation
- NemoTek licenses Tessera’s wafer-level camera and wafer-level packaging technologies
- Licensees ship more than 20 billion units using Tessera Compliant Chip® (TCC) CSP technology

2007

- Toshiba licenses OptiML Focus technology
- Tessera opens R&D center in Japan
- Tessera introduces µPILR interconnect platform and OptiML wafer-level camera technology
- Tessera acquires Eyesquad
- Advanced Packaging Magazine recognizes Tessera's wafer-level packaging technology
- Electronic Products Magazine recognizes OptiML WLC

2006

- Tessera acquires Digital Optics Corporation
- Tessera introduces SHELLCASE CF and SHELLCASE RT technologies
- Licensees ship more than 10 billion units using TCC technology
- Electronic Business Magazine ranks Tessera as 4th Fastest Growing Company
- Micron and Infineon license TCC chip scale packaging (CSP) technology

2005

- Tessera acquires Shellcase, Ltd.
- Ernst & Young names Bruce McWilliams Entrepreneur of the Year for No. Calif.
- BusinessWeek Magazine ranks Tessera as 2nd Hottest Growing Company

2004

- NxGen licenses Tessera µZ™ ball stack package
- Matsushita, NEC and Oki license Tessera CSP technology

2003

- Tessera completes successful initial public offering on Nasdaq
- R&D Magazine names µZ one of 100 most significant products of the year
- Electronic Product & Packaging Magazine recognizes µZ technology
- Advanced Packaging Magazine recognizes µZ technology

2002

- Rohm licenses Tessera CSP technology
- Tessera introduces µZ multi-chip family of packaging solutions
- Tessera places 2nd in MIT Technology Review Magazine's Patent Scorecard
- Tessera ranks 3rd in III's Annual Tech. Report: Advanced Semiconductor Packaging Patents

2001

- Tessera and Intel work together to develop stacked chip-scale packages
- Licensees ship more than 1 billion units using TCC technology
- Sharp licenses TCC CSP technology

2000

- Meicer licenses µBGA® technology
- Tessera and Toshiba sign µBGA technology agreement

1999

- ChipMOS, EEMS and Toshiba license µBGA technology
- Tessera and LG Electronics sign µBGA technology agreement

1998

- Sharp becomes 20th licensee of Tessera packaging technology
- Rambus chooses µBGA technology as reference package for RDRAM

1997

- Samsung selects Tessera µBGA package for high volume SRAM production
- Red Herring Magazine recognizes Tessera as one of top technology companies

1996

- Intel adopts µBGA for flash memory devices

1995

- Electronic Product & Packaging Magazine recognizes µBGA technology

1994

- Hitachi licenses Tessera packaging technology
- Shinko Electric Industries Ltd. licenses Tessera technology

1993

- R&D Magazine recognizes Tessera's multi-chip module system

1990

- Tessera's TCC CSP technology patented
- Tessera founded by former IBM research scientists